Wetting of Mono and Few-Layered WS$_2$ and MoS$_2$ Films Supported on Si/SiO$_2$ Substrates

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ABSTRACT The recent interest and excitement in graphene has also opened up a pandora’s box of other two-dimensional (2D) materials and material combinations which are now beginning to come to the fore. One family of these emerging 2D materials is transition metal dichalcogenides (TMDs). So far there is very limited understanding on the wetting behavior of “monolayer” TMD materials. In this study, we synthesized large-area, continuous monolayer tungsten disulfide (WS$_2$) and molybdenum disulfide (MoS$_2$) films on SiO$_2$/Si substrates by the thermal reduction and sulfurization of WO$_3$ and MO$_3$ thin films. The monolayer TMD films displayed an advancing water contact angle of $\sim$83° as compared to $\sim$90° for the bulk material. We also prepared bilayer and trilayer WS$_2$ films and studied the transition of the water contact angle with increasing number of layers. The advancing water contact angle increased to $\sim$85° for the bilayer and then to $\sim$90° for the trilayer film. Beyond three layers, there was no significant change in the measured water contact angle. This type of wetting transition indicates that water interacts to some extent with the underlying silica substrate through the monolayer TMD sheet. The experimentally observed wetting transition with numbers of TMD layers lies in-between the predictions of one continuum model that considers only van der Waals attractions and another model that considers only dipole–dipole interactions. We also explored wetting as a function of aging. A clean single-layer WS$_2$ film (without airborne contaminants) was shown to be strongly hydrophilic with an advancing water contact angle of $\sim$70°. However, over time, the sample ages as hydrocarbons and water present in air adsorb onto the clean WS$_2$ sheet. After $\sim$7 days, the aging process is completed and the advancing water contact angle of the aged single-layer WS$_2$ film stabilizes at $\sim$83°. These results suggest that clean (i.e., nonaged) monolayer TMDs are hydrophilic materials. We further show that substitution of sulfur atoms by oxygen in the lattice of aged monolayer WS$_2$ and MoS$_2$ films can be used to generate well-defined ‘hydrophobic–hydrophilic’ patterns that preferentially accumulate and create microdrop arrays on the surface during water condensation and evaporation experiments.

KEYWORDS: wetting · monolayer transition metal dichalcogenides · wetting transparency · hydrophobicity · hydrophilicity · microdrop arrays · condensation dynamics

Understanding how water wets a solid surface is a classic problem in surface science and is important for both fundamental understanding and practical applications.1–3 Recently, there has been intense activity in understanding how water wets mono and few-layered graphene surfaces.4–12 Since such experiments are challenging to perform on suspended (i.e., free-standing) graphene, the experiments are typically performed on supported graphene sheets. For graphene, it has been shown that the underlying (supporting) substrate4–7,11 can exert an influence on the wetting of the monolayer graphene sheet and this effect is controlled by various factors such as the composition of the substrate, presence of charge traps in the substrate, cleanliness (or aging) of the graphene sheet and defects in the graphene. In general, these effects result in a partial transmission of the van der Waals interactions between the underlying substrate and the water droplet resulting in a partial

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wetting transparency effect\textsuperscript{5–10} for monolayer graphene. For thicker or few-layer graphene films (>1 nm thick), such effects disappear, and from a wetting standpoint, the graphene film is completely decoupled from the underlying substrate.

While we have a reasonable understanding of how water wets supported mono and few layered graphene films on substrates, there is not a clear understanding on the wettabilitiy of two-dimensional (2D) transition metal dichalcogenides (TMDs). One study\textsuperscript{13} has reported wetting measurements on crystalline sheets of molybdenum disulfide (MoS\textsubscript{2}). The water contact angle is higher for monolayer (~98°) and drops to ~95° for bilayer MoS\textsubscript{2}. Bulk samples show water contact angle of ~88°. However, the chemical vapor deposition process used in this study involved the use of reduced graphene oxide, that is spin coated as a supporting layer. The wetting contact angle is decoupled from the underlying substrate.

Such a chalcogen substitution approach provides a facile means to control the spatial wettability of molybdenum disulfide (MoS\textsubscript{2}). The water contact angle is higher for monolayer (>1 nm thick), such effects disappear, and from a wetting standpoint, the graphene film is completely decoupled from the underlying substrate.

For thicker or few-layer graphene films, surface roughness features that could affect the water contact angle measurements. Most importantly, this study\textsuperscript{13} did not explore the effects of aging, which are known to be very significant\textsuperscript{9} for other 2D materials such as graphene. To address these issues, we have systematically studied the wetting properties of monolayer, bilayer, trilayer and multilayer tungsten disulfide (WS\textsubscript{2}) films on Si/SiO\textsubscript{2} substrates and compared our results to the predictions of simple continuum wetting models based on the effective interface potential approach. We report a partial (albeit weak) wetting transparency effect for WS\textsubscript{2} monolayers which lies in-between the predictions of one continuum model that considers only van der Waals attractions and another model that considers only dipole–dipole interactions.

The wetting contact angle of monolayer MoS\textsubscript{2} on Si/SiO\textsubscript{2} substrate was also measured and was found to be close to that of monolayered WS\textsubscript{2}. Further, we investigated “aging” effects in monolayer WS\textsubscript{2} films and demonstrate that when all airborne contaminants are desorbed from the sample surface, the monolayer film is in fact strongly hydrophilic and not hydrophobic as was reported in ref 13. Over a period of ~1 week, these airborne contaminants are re-established on the monolayered WS\textsubscript{2} surface and the advancing water contact angle reverts back to ~83°. Finally, we study the effect of substitution of chalcogen (S) with oxygen groups within the monolayered TMD (WS\textsubscript{2} and MoS\textsubscript{2}) surfaces. The aged TMD surface is nearly hydrophobic, whereas the oxygen substituted region is far more hydrophilic thus enabling controllable ‘hydrophilic–hydrophobic’ patterns to be engineered on the surface. Such patterning allows liquid microdrops arrays to preferentially nucleate and grow on the hydrophilic patches during water condensation experiments. Such a chalcogen substitution approach provides a facile means to control the spatial wettability distribution of TMD films for applications in micro and nanofluidics.

TMDs have the stoichiometric formula, MX\textsubscript{2}, with a trigonal prismatic structure\textsuperscript{14} composed of atomic layers of chalcogens (X = S, Se, Te) and group-VI transition metals (M = Mo, W). They are stable in the bulk form but also as few-layered as well as monolayer sheets. It is well understood that an individual monolayer of trigonal prismatic semiconducting TMDs (such as MoS\textsubscript{2} and WS\textsubscript{2}) exhibit a direct band gap\textsuperscript{15,16} which is not present in few-layered systems. For this reason, monolayer TMDs exhibit remarkably enhanced interaction with visible light due to this indirect-to-direct bandgap conversion at the monolayer limit, thus rendering these systems versatile platforms for studying light-matter interactions.\textsuperscript{17,18} In particular, there are a number of emerging applications in which monolayer MoS\textsubscript{2}/WS\textsubscript{2} has been utilized\textsuperscript{19–30} in membranes, batteries and biosensors, all applications where the material inevitably comes in compact with aqueous media. Understanding how water interacts with and wets such surfaces is important for the above applications, which is the goal of our study. The wetting studies are performed for TMD films supported on Si/SiO\textsubscript{2} substrates since this is the most common gate dielectric for TMD based devices.

RESULTS AND DISCUSSION

Thin films of WS\textsubscript{2} were prepared by a thermal reduction/sulphurization method which is described in our previous work.\textsuperscript{31} Briefly, this process involves depositing a thin film of tungsten trioxide (WO\textsubscript{3}) on a Si/SiO\textsubscript{2} substrate by thermal evaporation at a base pressure of ~5 × 10\textsuperscript{-7} Torr. The films were then loaded into a quartz tube furnace and heated to ~800 °C under a low pressure argon environment. A sulfur target was also placed upstream of the hot zone of the furnace as shown in Figure 1a. The target was independently heated using a heating belt to evaporate the sulfur. When the furnace temperature reached ~800 °C, the metal oxide film was reduced completely and thinned down to a continuous atomically thin layer. At this stage the heating belt temperature was raised to about 150 °C in order to release sulfur into the furnace hot zone. After ~30 min of reaction, the heating elements were switched off and the furnace was allowed to cool naturally. A similar process was also utilized to grow monolayer MoS\textsubscript{2} films from a MoO\textsubscript{3} precursor. The as-produced TMD films were continuous, as demonstrated by optical microscopy (Figure 1b), atomic force microscopy (AFM) and scanning electron microscopy (Figure 1c). AFM confirmed the average thickness (Figure 1c,d) of our as-synthesized monolayer WS\textsubscript{2} films to be ~1 nm, comparable to the theoretical thickness of 1.23 nm for single-layer WS\textsubscript{2}. In addition to monolayers, we also synthesized bilayer, trilayer and multilayer (>10 layers) WS\textsubscript{2} films.
This was achieved by varying the WO$_3$ precursor film thickness. In general, very thin oxide films (~1–2 nm thick) produce monolayer WS$_2$, while bilayer, trilayer, and multilayer films could be produced by increasing the thickness$^{31}$ of the oxide precursor films.

Raman spectroscopy was used to characterize the few-to-single-layer WS$_2$ films using the 532 nm excitation wavelength in a confocal microscopy configuration (Figure 2). Prior to the Raman study, AFM line scans (see Figure 1c,d) were used to independently confirm the number of WS$_2$ layers in these films. The positions and intensities (Figure 2) of the 2LA(M), E and A peaks (obtained by Lorentzian fitting) are consistent$^{31–33}$ with those expected for WS$_2$. While the intensities (Figure 2a) of the above modes did change from mono- to bi- to trilayer films, the intensity ratio of these modes (e.g., E to A) did not show any definitive trend with respect to the number of layers. In addition, the frequency difference between the A and E and 2LA(M) modes showed a clear increase from monolayer to bilayer to trilayered films as shown in Figure 2b. This is because as the number of layers decreases, the A mode is freer to vibrate in the out-of-plane direction and, therefore, has decreased frequency as opposed to the in plane modes. In this way, Raman spectroscopy characterization provides additional confirmation regarding the number of TMD layers in the film. Raman spectroscopy mapping (as in Figure 2c and Supporting Information Figure S1) was also used to confirm the uniformity of the TMD samples on the SiO$_2$/Si substrate.

Advancing water contact angle measurements were performed using a 500-F4 Rame-Hart goniometer for images, and the low-bond axisymmetric drop shape analysis technique$^{32}$ was used to determine the contact angles. In the experiments, a $\sim$1 μL volume water drop was brought in contact with the surface, and subsequently, the volume of the drop was increased and then decreased to advance and retract the liquid front. This was repeated several times in order to confirm the reproducibility of our results. All the tests were carried out in an air environment at room temperature (~20 °C) and relative humidity of ~70%. We chose to measure the advancing contact angle as opposed to the static contact angle since our samples showed significant wetting hysteresis (20–30°), which results in large scattering in the static contact angle data. Figure 3a shows the advancing water contact angles for the monolayer, bilayer, trilayer, and multilayer (bulk) WS$_2$ samples as well as the baseline Si/SiO$_2$ substrate. The SiO$_2$ substrate is strongly hydrophilic with an advancing water contact angle of ~30°. This is expected and is due to the formation of hydrogen bonding networks at the water-SiO$_2$ interface which drastically increases the affinity of water to the solid surface.$^5$ When a monolayer of WS$_2$ is deposited on the Si/SiO$_2$ substrate, the advancing water contact angle jumps to ~83°; we expect this is because hydrogen bonds between water and the SiO$_2$ surface can no longer develop due to the presence of the WS$_2$ film at the interface. Interestingly, the bilayer and trilayer films were more hydrophobic when compared to the monolayer film, and showed advancing wetting angles of ~85° and ~90°, respectively. There was no measurable difference between the trilayer and bulk samples (>10 layers) as depicted in Figure 3a. In addition to WS$_2$, we also tested monolayered MoS$_2$ on a SiO$_2$/Si wafer, and the measured advancing water contact angle was
A monolayer WS2 placed on silica increases the water contact angle close to WS2. The contact angle for water on bulk WS2 is 5.63 ± 0.2°, whereas the contact angle for monolayer WS2 is 1.40 ± 0.2°. The work of adhesion for water on bulk WS2 is 5.03 ± 0.2 J/m², and for monolayer WS2, it is 5.63 ± 0.2 J/m². After fitting the predicted water contact angle on silica and water on bulk WS2, the Hamaker constant is found to be 1.35 ± 0.05 J m⁻⁶ and 1.40 ± 0.05 J m⁻⁶, respectively.

For the situation of water on the SiO₂ substrate with WS₂ in-between, the interfacial energy (assuming the van der Waals interactions in a 12–6 Lennard-Jones form) can be expressed as

\[
W(h) = \frac{C_{\text{WS}_2 - \text{SiO}_2}}{h^6} - \frac{C_{\text{H}_2\text{O} - \text{WS}_2}}{(h+d)^8} + \frac{C_{\text{H}_2\text{O} - \text{SiO}_2}}{(h+d)^8} - \frac{A_{\text{H}_2\text{O} - \text{WS}_2}}{12\pi h^2} - \frac{A_{\text{H}_2\text{O} - \text{SiO}_2}}{12\pi(h+d)^2} - \frac{A_{\text{WS}_2 - \text{SiO}_2}}{12\pi(h+d)^2} \tag{1}
\]

where \( h \) is the separation between water and the substrate, \( d \) is the thickness of the WS₂ film, \( A_{\text{H}_2\text{O} - \text{WS}_2} \) is the Hamaker’s constant for water on bulk WS₂, \( A_{\text{H}_2\text{O} - \text{SiO}_2} \) is the Hamaker’s constant for water on bulk SiO₂, while the constants \( C_{\text{H}_2\text{O} - \text{WS}_2} \) and \( C_{\text{H}_2\text{O} - \text{SiO}_2} \) capture short-range repulsion between water and the substrate and are obtained by fitting the predicted water contact angles for water on silica and water on bulk WS₂ to the experimentally measured values. Note that when \( d = 0 \), eq 1 reduces to the correct form for the work of adhesion for water on silica substrate, and when \( d \) approaches infinity, eq 1 reduces to the correct form for water on bulk WS₂. Once the work of adhesion (the negative of interfacial energy) and the surface free energy are known, the water contact angle (θ) can be calculated from the Young–Dupre equation:

\[
\gamma(1 + \cos \theta) = W_{\text{ad}} = \left| W(h) \right| \tag{2}
\]

The surface tension of water \( \gamma \) is taken as 0.072 J/m². A challenge associated with this work is the lack of experimental reports on the Hamaker’s constant for monolayer WS₂ and bulk WS₂. Therefore, we had to resort to theoretical estimation (details can be found in the Supporting Information). On the basis of our analysis, the Hamaker constant is \( A_{\text{H}_2\text{O} - \text{SiO}_2} \) = 5.03 × 10⁻¹⁹ J and \( A_{\text{H}_2\text{O} - \text{WS}_2} \) = 5.63 × 10⁻¹⁹ J. After fitting the predicted water contact angle on silica and water on bulk WS₂, to the experimentally measured values of ~30° and ~90°, respectively, we obtained \( C_{\text{H}_2\text{O} - \text{SiO}_2} \) = 1.35 × 10⁻⁸² J m⁻⁶ and \( C_{\text{H}_2\text{O} - \text{WS}_2} \) = 1.40 × 10⁻⁸¹ J m⁻⁶. The equilibrium separations \( h \) are found to be ~0.86 Å and ~1.25 Å for water on silica and water on WS₂, respectively.

Once all of the above constants are known, the relationship between the interfacial energy (and the contact angle: eqs 1 and 2), and the thickness of the WS₂ film can be established. Figure 3b shows our predictions for the contact angles for water on silica with different numbers of layers of WS₂ using the classical continuum model (eq 1 and eq 2). The thickness of an individual WS₂ monolayer is assumed to be ~1.23 nm in the calculation. The calculation indicates complete opacity of the WS₂ monolayer, i.e., even a single sheet of WS₂ placed on silica increases the water contact angle from the value of silica to the value of bulk WS₂. There is no wetting transition in the continuum model which contradicts the experiments. This result holds whether we use the Hamaker’s constant for bulk WS₂ or for monolayer WS₂ (see Supporting Information). Such discrepancy between the continuum wetting model and our experiments could be caused by the presence of defects in the WS₂ film (S and W vacancies are commonly observed in TMD films grown by vapor phase nucleation and growth methods). High-resolution transmission electron microscopy (HRTEM) imaging of monolayer WS₂ sheets grown by our thermal reduction and sulfurization methods.
method does indeed indicate the presence of such defect sites (Supporting Information Figure S3). Another possibility is presence of charge traps or charge puddles that are ubiquitous in Si/SiO$_2$ substrates.\textsuperscript{37,38} The trapped charges may result in a relatively long-range (dipole—dipole) electrostatic interaction with water which could increase the affinity of water to the surface and hence reduce the wetting contact angle. After about three layers (>3 nm thickness) of WS$_2$, this effect is presumably screened out and the effect of the substrate is no longer felt on the wetting of the TMD film.

To understand the effect of such long-range electrostatic coupling, we also developed a model that includes the fixed dipole (on silica surface) interaction with fixed dipole (of ordered water molecules near the interface) with a 1/r$^2$ decaying tail,\textsuperscript{34,36} instead of the van der Waals attraction that scales with 1/r$^6$ Å. As such, charges on silica surfaces\textsuperscript{37,38} and the resulting ordering of the water molecules near the interface.\textsuperscript{39} Following the same integration method,\textsuperscript{34} we can obtain the interfacial energy as

$$V(h) = \frac{C_{\text{H}_2\text{O} - \text{Substrate}}}{h^6} - A_{\text{H}_2\text{O} - \text{Substrate}} \left( h \log \frac{h}{h+t} - t \log \frac{h+t}{h+k+t} + (h+k) \log \frac{h+k}{h+k+t} \right) \quad (3)$$

where $h$ is the separation between water and the substrate, $k$ and $t$ are the thickness of the fixed dipole layers in water and the substrate. The following trend is rather insensitive to the choice of $k$ or $t$ between 1 and 5 Å. As such, $k$ and $t$ are taken as 2 Å. $A_{\text{H}_2\text{O} - \text{Substrate}}$ relates to the interaction strength, which is proportional to the dipole strength and dipole density in water and the substrate. As the dipole distribution and strength in the water layer and SiO$_2$ substrate are not known, we treat $A_{\text{H}_2\text{O} - \text{Substrate}}$ as a fitting parameter. For simplicity, the repulsion term ($C$ in eq 3) is assumed to be identical to the van der Waals repulsive interaction described in eq 1. From the wetting angle of water on SiO$_2$ and water on WS$_2$, $A_{\text{H}_2\text{O} - \text{SiO}_2}$ and $A_{\text{H}_2\text{O} - \text{WS}_2}$ can be calculated as $1.0 \times 10^9$ and $6.4 \times 10^8$ J/m$^3$, respectively. Thus, the total interaction between water, WS$_2$, and SiO$_2$ can be expressed as

$$V_{\text{total}}(h) = V_{\text{H}_2\text{O} - \text{WS}_2}(h) + V_{\text{H}_2\text{O} - \text{SiO}_2}(h + nd) \quad (4)$$

where $n$ is the number of layers of WS$_2$ and $d$ is the thickness of one layer of WS$_2$ (12 Å). By minimizing $V_{\text{total}}$ as a function of $h$, we can calculate the interfacial energy as a function of $n$. Then, using eq 2, we can obtain the wetting angle as a function of $n$. As shown in Figure 3b, the wetting angle exhibits a transition from $\sim$28° to $\sim$90° over a few layers of separation. The VdW-model and the dipole-model provide two limiting conditions to comprehend the wetting transition, with the experimental value somewhat in-between. The result supports the notion that the wetting angle transition (with number of WS$_2$ layers) observed in the experiments is caused by long-range permanent dipole-permanent dipole interactions.

Another key issue pertaining to the water contact angle measurements is the recognition that all samples age over time. The samples tested so far were all characterized for their wetting properties several weeks after they were first synthesized. Aging involves adsorption of airborne contaminants (mainly hydrocarbons but also water) on the surface of the TMD sheets. Recently, it was demonstrated\textsuperscript{9} that monolayer graphene and graphite surfaces in the absence of such contaminants are hydrophilic and not hydrophobic. To investigate such aging effects and their impact on the wettability of TMD sheets, we heated a WS$_2$ monolayer on Si/SiO$_2$ in an inert Ar atmosphere to $\sim$550 °C for $\sim$1 h, and then allowed the sample to cool back to room temperature in the Ar atmosphere. Heating to $\sim$550 °C has been shown to successfully desorb the majority of airborne contaminants from graphene and graphitic surfaces. After cooling to room temperature, this clean (or fresh) sample was immediately transferred in a gastight container filled with Ar to the contact angle measuring setup and its wetting response was recorded on exposure to ambient air (Figure 3c). The result indicates that the advancing water contact angle increased rapidly from $\sim$70° (our initial data point was taken $\sim$5 min after the start of the aging process) to $\sim$77° in $\sim$20 min. Subsequently, the advancing water contact angle continued to rise gradually over a period of $\sim$1 week, and finally stabilized at $\sim$83° which matches very well the result in Figure 3a for an aged WS$_2$ monolayer. While the effect of airborne hydrocarbon contaminants cannot be avoided in practical situations, it is important to recognize that similar to graphene, perfectly clean TMD monolayers are intrinsically “hydrophilic” and not hydrophobic. After $\sim$1 week, the aging process appears to reach equilibrium, with the water contact angle stabilizing and then remaining constant at further times. It should be noted that the TMD nanosheets used in practical applications are likely to represent such fully aged samples that exhibit close to hydrophobic behavior.

Another noteworthy feature of TMDs is that even a single-layer of WS$_2$ or MoS$_2$ is a composite of a relatively more hydrophilic metal and a relatively less hydrophilic chalcogen atom. The chalcogen atom (as for example Sulfur), could potentially be expelled from the structure by exposing it to Argon (Ar) plasma bombardment. The replacements for the chalcogens are possibly oxygen from the ambient (oxygen gas, water vapor etc.) which will likely occupy the sulfur vacancy sites. Oxygen is known to be hydrophilic due to its propensity to form hydrogen bonds\textsuperscript{14} with water molecules. As a result, such oxygen doped TMD sheets are expected to be more hydrophilic compared to the
original TMD sheet. We used Ar plasma bombardment to create hydrophilic regions in a hydrophobic (aged) WS₂ monolayer by depleting it of sulfur. The plasma treatment was performed using a commercial plasma cleaning system (NanoClean Fischione Instruments Model 1070). As-grown WS₂ films on SiO₂-covered (300 nm) silicon substrates were subjected to a ∼50W plasma operating at ∼200 mTorr and ambient temperature. Core-level X-ray photoelectron spectroscopy (XPS) was used to obtain chemical composition and bonding information in the WS₂ film as a function of plasma treatment (Figure 4). The W 4f spectra (Figure 4a) clearly show a plasma-induced spectral line shape change with increased intensity toward higher binding energies. The convoluted spectra were fit with low (Wₗ₀w)- and high (Wₗₒₜₜ)-oxidation state photoelectron doublets with 4f₇/₂ peak energies at 32.8 and 35.9 eV, consistent with W⁺/C₀S and W⁺/C₀O bonding observed in WS₂ and WO₃, respectively. The core-level O 1s spectra are dominated (Figure 4a) by a contribution (Oₗₒₜₜ) from the SiO₂ substrate at 532.6 eV. However, an additional low-energy shoulder at 530.7 eV (Oₗₒₜₜ) grows with successive plasma treatment (Figure 4a). The position of the low-energy feature is consistent with literature values for oxygen bonded to tungsten.⁴⁰ We do not believe that this contribution stems from adventitious hydrocarbon contamination, as we observed a monotonic decrease in the C 1s peak intensity with plasma treatment (Supporting Information Figure S4). We also observed nitrogen in the sample, but no obvious trend in N 1s intensity versus plasma treatment could be discerned (as shown in the Supporting Information Figure S4). Representative sulfur 2p spectra are shown in rightmost panel of Figure 4a. Peak fitting revealed two separate contributions, with 2p₃/₂ peaks centered at 162.3 eV (Sₗₒₜₜ) and 163.6 eV (Sₗₒₜₜ) in WS₂. The Sₗₒₜₜ contribution stems from S=–W bonding in WS₂. The Sₗₒₜₜ feature is present only in the untreated films and disappears with plasma treatment. This could stem from unreacted sulfur present on the surface.

To study the plasma-induced compositional changes in the sample, we compared the integrated intensities of the elements using standard relative sensitivity factors in Figure 4b. We first note the dramatic decrease in the S:W ratio as a function of plasma treatment. The S:W > 2 in the untreated sample could be due to residual sulfur on the surface of the sample from the growth process, which is supported by the presence of the high-energy sulfur contribution (Sₗₒₜₜ) in Figure 4a. We additionally plot, on the same axis, the W:Si ratio, which is relatively constant. This indicates that sulfur atoms are being preferentially removed from the film by the Ar plasma treatment. The low-energy oxygen contribution, attributed to W⁺/C₀O bonding, increases with respect to the W 4f intensity for successive plasma treatments, as shown by the Oₗₒₜₜ/W ratio in Figure 4b. These results suggest the gradual removal of sulfur atoms from each WS₂ coordination unit, causing formation of units with the general formula WSₓOᵧ, where the W atom remains in a high oxidation state. The data presented here supports a mechanism of direct exchange between sulfur and oxygen atoms due to the plasma treatment. The increased oxygenation of the film tends to oxidize the central tungsten atoms, which is further supported by the direct relationship between the Wₗₒₜₜ and Oₗₒₜₜ features, as shown in Figure 4c. Such sulfur substitution at vacancy defect sites has been previously observed in high-resolution transmission...
METHODS

Water Contact Angle Measurements. Advancing water contact angle measurements were performed using a 500-F4 Rame-Hart goniometer for images, and the low-bond axisymmetric drop shape analysis technique\(^{12}\) was used to determine the contact angles. In the experiments, a \(\sim 1\) \(\mu\)L volume water drop was brought in contact with the surface, and subsequently, the volume of the drop was increased and then decreased to advance and retract the liquid front. All the tests were carried out in an air environment at room temperature \((\sim 20^\circ C)\) and relative humidity of \(\sim 70\%\). For statistics, we tested between 3 and 5 different samples for each test case with about a dozen measurements performed at different locations on each sample.

X-ray Photoelectron Spectroscopy (XPS). The WS\(_2\) films were loaded into a PHI5400 spectroscopy chamber, equipped with electron microscopy experiments in exfoliated WS\(_2\) and MoS\(_2\) monolayers.\(^{42,43}\)

We took advantage of such chalcogen substitution phenomena to engineer hydrophilic–hydrophobic patterns on the same monolayer samples. For this, a silicon wafer patterned with a periodic array of \(\sim 100 \mu\)m size holes was used to selectively mask certain regions of the WS\(_2\) monolayer film during a 20 s argon plasma irradiation treatment cycle. Water condensation tests were performed in ambient air at a temperature of \(\sim 20^\circ C\) and a relative humidity of \(\sim 70\%\), corresponding to a dew point temperature of \(\sim 16^\circ C\). The testing apparatus was installed under a high resolution optical microscope. The sample was horizontally put on a cold plate, which was controlled at \(\sim 4^\circ C\) by a circulating chiller. After the condensation experiment, the temperature of the cooling stage was increased to \(\sim 30^\circ C\) gradually. The evaporation of the water drops was recorded using the same resolution as the condensation experiment. The condensation result is shown in Figure 5a for the WS\(_2\) film. The top panel in Figure 5a shows the water condensation on monolayer WS\(_2\) without plasma treatment, indicating liquid drops nucleating at random locations on the film surface.

By contrast, for the plasma treated WS\(_2\) film (lower panel of Figure 5a), we observed nucleation and growth of water drops on the highly hydrophilic regions with diameters of \(\sim 100 \mu\)m, which correlates well to the size of the opening in the mask that was placed on the sample during the plasma treatment. Clearly, these oxygen doped regions are far more hydrophilic and attract water during condensation. The net result of this is that we can pattern liquid microdrop arrays on such surfaces in a facile manner with important implications in microfluidics. This idea could in principle be extended to nanodrops by using a pattern with nanopores rather than the \(\sim 100 \mu\)m size pores that were used in this experiment. These results were also reproducible for monolayer MoS\(_2\) (Figure 5b). The top panel shows random nucleation of drops on the hydrophilic (i.e., aged) MoS\(_2\) surface. By contrast, after exposing it to \(\sim 20\) s of Ar plasma through the aforementioned mask with periodic array of \(\sim 100 \mu\)m size openings, the distribution of water clusters is no longer random and follows a periodic pattern that matches the pattern of the mask though which the plasma treatment was carried out (bottom panel of Figure 5b). After water condensation for about 1 to 2 min, the samples were gradually heated to \(\sim 30^\circ C\) and the water drops were evaporated off the sample surface without damaging the TMD film (see Supporting Information Figure S5).

CONCLUSIONS

In summary, this work provided fundamental information on the wettability of mono and few-layered films of TMDs supported on silicon/silicon-dioxide wafers. The results indicate a noticeable (but weak) effect of the substrate on the wetting of the TMD film, which is in-between the predictions of one continuum model that considers only van der Waals interactions and another model that considers only dipole–dipole interactions. We also demonstrate that TMDs undergo a powerful aging effect as airborne contaminants are established on the film surface. This aging was shown to mask the intrinsic hydrophilicity of monolayer TMD materials to a great extent. Finally, we show the principle of chalcogen (sulfur) substitution with oxygen in TMDs to engineer well-controlled hydrophobic–hydrophilic patterns on the same monolayer TMD sheet. Such patterns can be used to construct periodic arrays of liquid drops on surfaces in a facile and effective manner.

Figure 5. (a) (Top) Condensation of water drops on untreated WS\(_2\); scale bar is \(\sim 100 \mu\)m. (Bottom) Condensation on plasma-patterned WS\(_2\) surface; scale bar is \(\sim 200 \mu\)m. (b) Top and bottom show corresponding condensation results for untreated and plasma-patterned monolayer MoS\(_2\) film; the scale bar is \(\sim 100 \mu\)m for the top panel and \(\sim 200 \mu\)m for the bottom panel.
a monochromatic Al Ka source (λ = 1486.6 eV), approximately 1 min after each plasma treatment. The detector pass energy was set to 23.5 eV and the surface-to-detector takeoff angle was set at θ = 30° to enhance the sensitivity of the thin WS2 overlayers. A beam energy (∼1 eV) argon ion flux incident on the sample was used to mitigate charging effects. The substrate Si 2p line at 103.3 eV was used for binding energy calibration.

Water Condensation and Evaporation Experiments. The tests were performed in ambient air at a temperature of ∼20 °C and a relative humidity of ∼70%, corresponding to a dew point temperature of −16 °C. The testing apparatus was installed under a high-resolution optical microscope. The sample was horizontally put on a cold plate, which was controlled at −4 °C by a circulating chiller. After the condensation experiment, the temperature of the cooling stage was increased to 30 °C vertically. The evaporation of water droplets on the sample treated monolayer MoS2 sheet was recorded using the same resolution as the condensation experiment.

Conflict of Interest: The authors declare no competing financial interest.

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Supporting Information Available: Detailed derivation of the Hamaker’s constant for bulk WS2 and for monolayer WS2, Raman mapping of monolayer MoS2, contact angle measurement for monolayer MoS2 sheet on an Si/SiO2 substrate, high-resolution transmission electron microscopy (HRTEM) imaging of defects in monolayer WS2, C 1s and N 1s intensity from X-ray photoelectron spectroscopy of plasma treated WS2 samples, and optical images showing the evaporation of water droplets on plasma treated monolayer MoS2. This material is available free of charge via the Internet at http://pubs.acs.org.

REFERENCES AND NOTES